

Semiconductor devices — Mechanical and climatic test methods —

**Part 27: Electrostatic discharge (ESD)
sensitivity testing — Machine
model (MM)**

ICS 31.080.01

National foreword

This British Standard is the UK implementation of EN 60749-27:2006+A1:2012. It is identical to IEC 60749-27:2006 incorporating amendment 1:2012. It supersedes BS EN 60749-27:2006, which is withdrawn.

The start and finish of text introduced or altered by amendment is indicated in the text by tags. Tags indicating changes to IEC text carry the number of the IEC amendment. For example, text altered by IEC amendment 1 is indicated by A1 A1.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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**Semiconductor devices -
Mechanical and climatic test methods
Part 27: Electrostatic discharge (ESD) sensitivity testing -
Machine model (MM)
(IEC 60749-27:2006)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques
Partie 27: Essai de sensibilité aux
décharges électrostatiques (DES) -
Modèle de machine (MM)
(CEI 60749-27:2006)

Halbleiterbauelemente -
Mechanische und klimatische
Prüfverfahren
Teil 27: Prüfung der Empfindlichkeit
gegen elektrostatische Entladungen
(ESD) -
Machine Model (MM)
(IEC 60749-27:2006)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/1861/FDIS, future edition 2 of IEC 60749-27, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-27 on 2006-08-01.

The following dates were fixed:

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- latest date by which the national standards conflicting
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Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-27:2006 was approved by CENELEC as a European Standard without any modification.

Foreword to amendment A1

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The text of the International Standard IEC 60749-27:2006/A1:2012 was approved by CENELEC as a European Standard without any modification.

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